

RD Number: RD136

RD Title: TB67S149HG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C1	1	0.1μF 100V	—	—	Chip capacitor	3.2mmX1.6mm	
2	C3	1	0.1μF 100V	—	—	Chip capacitor	3.2mmX1.6mm	
3	C4	1	100μF 50V	—	—	Electrolytic capacitor		
4	C5	0	0.1μF 100V	—	—	Chip capacitor	3.2mmX1.6mm	✓
5	C6	0	0.1μF 100V	—	—	Chip capacitor	3.2mmX1.6mm	✓
6	C7	0	0.1μF 100V	—	—	Chip capacitor	3.2mmX1.6mm	✓
7	C8	0	0.1μF 100V	—	—	Chip capacitor	3.2mmX1.6mm	✓
8	R_ERR	1	10kΩ 0.125W	—	—	Chip resistor	3.2mmX1.6mm	
9	R_ALM	1	10kΩ 0.125W	—	—	Chip resistor	3.2mmX1.6mm	
10	R_MO	1	10kΩ 0.125W	—	—	Leaded resistor		
11		2	Socket pin	—	—	Socket pin		
12	R4	0	Not mount	—	—	Leaded resistor		✓
13		0	Socket pin	—	—	Socket pin		✓
14	R_OSCM	1	10kΩ 0.125W	—	—	Leaded resistor		
15		2	Socket pin	—	—	Socket pin		
16	R_VRF1	1	2.5kΩ 0.125W	—	—	Leaded resistor		
17		2	Socket pin	—	—	Socket pin		
18	R_VRF2	1	2.5kΩ 0.125W	—	—	Leaded resistor		
19		2	Socket pin	—	—	Socket pin		
20	D1	1	CMZ36	CMZ36	TOSHIBA	Zener diode	M-FLAT	
21	CW/CCW	1	Pin header 3P	—	—	Jumper	2.54mm pitch	
22		1	Jumper socket	—	—	Short pin	2.54mm pitch	
23	DMODE1	1	Pin header 3P	—	—	Jumper	2.54mm pitch	
24		1	Jumper socket	—	—	Short pin	2.54mm pitch	
25	DMODE2	1	Pin header 3P	—	—	Jumper	2.54mm pitch	
26		1	Jumper socket	—	—	Short pin	2.54mm pitch	

27	DMODE0	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
28		1	Jumper socket	–	–	Short pin	2.54mm pitch	
29	RESET	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
30		1	Jumper socket	–	–	Short pin	2.54mm pitch	
31	JMP7	0	Pin header 3P	–	–	Jumper	2.54mm pitch	✓
32		0	Jumper socket	–	–	Short pin	2.54mm pitch	✓
33	ENABLE	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
34		1	Jumper socket	–	–	Short pin	2.54mm pitch	
35	JP_VCC	1	Pin header 3P	–	–	Jumper	2.54mm pitch	
36		1	Jumper socket	–	–	Short pin	2.54mm pitch	
37	VCC	1	Check terminal	–	–	Logic pin		
38	ERR	1	Check terminal	–	–	Logic pin		
39	ALM	1	Check terminal	–	–	Logic pin		
40	CW/CCW	1	Check terminal	–	–	Logic pin		
41	DMODE1	1	Check terminal	–	–	Logic pin		
42	DMODE2	1	Check terminal	–	–	Logic pin		
43	MO	1	Check terminal	–	–	Logic pin		
44	DMODE0	1	Check terminal	–	–	Logic pin		
45	RESET	1	Check terminal	–	–	Logic pin		
46	CLK	1	Check terminal	–	–	Logic pin		
47	ENABLE	1	Check terminal	–	–	Logic pin		
48	VREF	1	Check terminal	–	–	Logic pin		
49	OSCM	0	Check terminal	–	–	Logic pin		✓
50	VM	1	Check terminal	–	–	Logic pin		
51	VM	1	Check terminal	–	–	Logic pin		
52	VCOM	0	Check terminal	–	–	Logic pin		✓
53	OUT_A+	1	Check terminal	–	–	Logic pin		
54	OUT_A-	1	Check terminal	–	–	Logic pin		
55	OUT_B-	1	Check terminal	–	–	Logic pin		
56	OUT_B+	1	Check terminal	–	–	Logic pin		
57	VDD	1	Check terminal	–	–	Logic pin		
58	GND	1	Check terminal	–	–	Logic pin		
59	GND	1	Check terminal	–	–	Logic pin		
60	GND	1	Check terminal	–	–	Logic pin		

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